



Integrated Device Technology, Inc.  
6024 Silver Creek Valley Road, San Jose, CA - 95138

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

<b>PCN #:</b> <b>A1605-01 (R1)</b> <b>DATE:</b> <b>26-Jul-2016</b> <b>Product Affected:</b> 4DB0226KA3AVG(8) 4DB0226KA3AVG/M 4DB0226KA3AVG8/M (built in FCCSP-53)  <b>Date Effective:</b> <b>18-Aug-2016</b>	<b>MEANS OF DISTINGUISHING CHANGED DEVICES:</b> <input type="checkbox"/> Product Mark      Lot # will have: <input checked="" type="checkbox"/> Back Mark        "RC" prefix for ASECL, Taiwan <input type="checkbox"/> Date Code <input type="checkbox"/> Other
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<b>Contact:</b> IDT PCN DESK  <b>E-mail:</b> <a href="mailto:pcndesk@idt.com">pcndesk@idt.com</a>	<b>Attachment:</b> <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No  <b>Samples:</b> Please contact your local sales representative for sample request.
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**DESCRIPTION AND PURPOSE OF CHANGE:**

<input type="checkbox"/> Die Technology <input type="checkbox"/> Wafer Fabrication Process <input type="checkbox"/> Assembly Process <input type="checkbox"/> Equipment <input type="checkbox"/> Material <input type="checkbox"/> Testing <input checked="" type="checkbox"/> Manufacturing Site <input type="checkbox"/> Data Sheet <input type="checkbox"/> Other	<p><b>Revision 1:</b> This revised notice is to correct typo made on substrate core material from E679 to E700GR.</p> <p>This notification is to advise our customers that IDT is adding ASE ChungLi, Taiwan as an alternate assembly facility for parts that are currently assembled at ASE Kaohsiung, Taiwan.</p> <p>There is no change to the moisture performance.</p> <p>Attachment I details the qualification results.</p>
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**RELIABILITY/QUALIFICATION SUMMARY:**  
Refer to qualification data shown in Attachment I.

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

**CUSTOMER COMMENTS:** \_\_\_\_\_

**IDT ACKNOWLEDGMENT OF RECEIPT:**

RECD. BY: \_\_\_\_\_      DATE: \_\_\_\_\_



**PRODUCT/PROCESS CHANGE NOTICE (PCN)**

**ATTACHMENT I - PCN # : A1605-01 (R1)**

**PCN Type:** Manufacturing Site - Alternate Assembly Location

**Data Sheet Change:** None

No change in moisture sensitivity level (MSL)

**Detail Of Change:**

This notification is to advise our customers that IDT is adding ASE ChungLi, Taiwan as an alternate assembly facility for parts that are currently assembled at ASE Kaohsiung, Taiwan.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	<b>Existing Assembly (ASE Kaohsiung, Taiwan)</b>	<b>Alternate Assembly (ASE ChungLi, Taiwan)</b>
Die Bump	Sn1.8Ag	Sn1.8Ag
Mold Compound	KE-G1250FC-20B	KE-G1250FC-20B
Substrate	ABF-GX13/E700GR core	ABF-GX13/E700GR core
Solder Balls	Sn98.25/Ag1.2/Cu0.50/Ni0.05	Sn98.25/Ag1.2/Cu0.50/Ni0.05



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### ATTACHMENT I - PCN # : A1605-01 (R1)

#### Qualification Information and Qualification Data:

**Affected Packages:** FCCSP-53

**Assembly Material:** Shown on page 2 of this attachment.

**Qual Plan & Results:** Tests are in accordance with JEDEC47 recommended tests.

**Qualification Vehicle:** FCCSP-53

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Solder Ball Shear Test	JESD22-B117	0/5	0/5	0/5
Bond Pull Strength Test	Mils-Std-883, M2011	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	0/25

\* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test